

Features:

1. Chip material: Gap(Green) and AlGaAs(Red)

2. Emitted color: Green and Red

3. Lens Appearance :Green Diffused

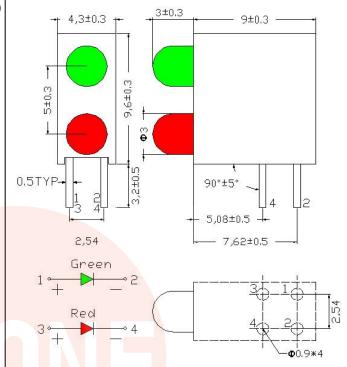
and Red Diffused

- 4. Designed for ease in circuit board assembly.
- 5. Black case enhance contrast ratio.
- 6. Solid state light source.
- 7. Reliable and rugged.
- 8. This product don't contained restriction substance, compliance RoHS standard.

Applications:

- 1. TV set
- 2. Monitor
- 3. Telephone
- 4. Computer
- 5. Circuit board

Package dimensions



Notes:

- 1. All dimensions are in millimeters (inches).
- 2. Tolerance is ±0.25mm (0.01") unless otherwise specified.
- 3. Lead spacing is measured where the leads emerge from the package.
- 4. Specifications are subject to change without notice.

■ Absolute Maximum Ratings(Ta=25°C)

Parameter	Symbol	Green	Red	Unit		
Power Dissipation	Pd	75	75	mW		
Forward Current	l _F	30	30	mA		
Peak Forward Current*1	I _{FP}	50	50	mA		
Reverse Voltage	V _R	Ę	V			
Operating Temperature	Topr	-30℃				
Storage Temperature	Tstg	-40℃				
Soldering Temperature	Tsol	260°C max (fo				
Hand Soldering Temperature	Tsol	350°C max(fo				

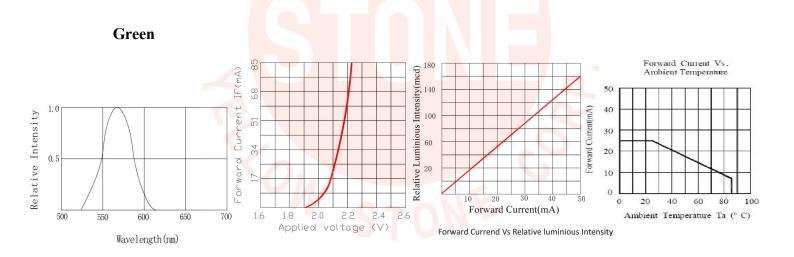
^{*1}Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

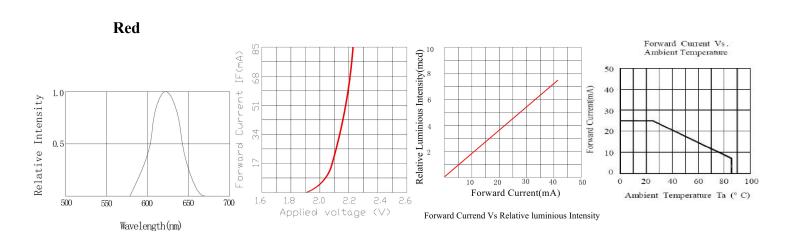


● Electrical and optical characteristics(Ta=25°C)

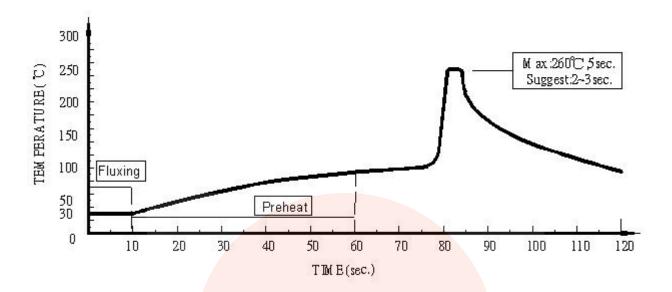
Parameter	Symbol	Condition	Color	Min.	Тур.	Max.	Unit
Forward Voltage	V _F	I _F =20mA	Green Red	1.8 1.8	2.2 2.2	2.6 2.4	V
Luminous Intensity	lv	I _F =20mA	Green Red	40 1	50 5	80 10	mcd
Reverse Current	I _R	V _R =5V	Green Red	-	-	10 2	μΑ
Peak Wave Length	λр	I _F =20mA	Green Red	-	-	-	nm
Dominant Wave Length	λd	I _F =20mA	Green Red	565 630	570 -	575 650	nm
Spectral Line Half-width	Δλ	I _F =20mA	Green Red	-	-	-	nm
Viewing Angle	2θ _{1/2}	I _F =20mA	Green Red	-	50 50	-	deg

■ Typical electro-optical characteristics curves





DIP Soldering



- 1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
- 2. DIP soldering and hand soldering should not be done more than one time.
- 3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temerature.
- 4. Avoid rapid cooling during temperature ramp-down process
- Although the soldering condition is recommended above,soldering at the lowest possible temperature is feasible for the LEDs

●IRON Soldering

A: Max: 350° C Within 3 sec. One time only.

B: The products of 3mm without flange, welding condition of flat plate PCB Max: 350° C Within 2 sec. One time only

